JET PROPULSION LABORATORY **INTEROFFICE MEMORANDUM**

TES DFM #978-4.1.1
10/13/00

TO : Design File

FROM : Ed Miller

SUBJECT: Spacecraft Interface Assembly (SCIF) HRCR Completion

REF: TES Design File Memo #937-4.2.1

The HRCR for the TES Spacecraft Interface Assembly (SCIF), ref. des. 2045SC01, was completed on 07/13/2000.

All action items generated at that review have now been closed.

A copy of the completed and signed HRCR form is attached, and is included with the End Item Data Package (EIDP). A hard copy of the EIDP may be found in the TES project files, in the I&T files, and in the JPL Vellum Files.

Electronic copies of all TES EIDP's are being made by optically scanning the packages. These electronic copies will be stored on compact disks which will be available from the TES project office upon completion of the scanning.

cc: TES Design File

TES Hardware Requirements Certification Review

Assembly/Subsystem	Cognizant Engineer	Phone	Section	Date
TES C& DH/SCIF	Jack Wooddell	393-3914	344	07/13/2000

Ref. Des.	Drawing No.	Dwg. Rev.	Serial No.	Nomenclature	Final IR	Op. Time or Cycles (if avail.)	Mass (Kg)
2045SC 01	2017042	A	FLT001	Spacecraft Interface Assembly (SCIF)	900758	180 Min. 5 cycles	0.762 w/o conformal coat

Check applicable answer and give necessary explanation in remarks column	Yes	No	N/A	Remarks	Data Attachments	Signature Approval & Date
1. Are all drawings and specifications complete, approved, released and frozen ?	☒	☐	☐		18. Latest Top Assembly Drawings ☒ Attached ☐ None	Cognizant Engineer
2. Do the released drawings and specifications reflect all approved changes?	☒	☐	☐		19. List of open ECRs ☐ Attached ☒ None	Cognizant SEM
3. Is hardware identical to other hardware delivered? If no, provide difference list.	☒	☐	☐		20. Waivers ☐ Attached ☒ None	Materials Engineer
4 Does the hardware meet the requirement of its FRs, specifications, waivers and/or ICDs ? If no, provide difference list. (See item 28 for reference.)	☒	☐	☐		21. Open MRBs ☐ Attached ☒ None	QA Engineer
5. Have all discrepancies and MRBs been dispositioned and agreed to by Engineering/ QA?	☒	☐	☐	Open IR #900202 to be closed	22. Open Problem Logs & P/FRs ☒ Attached ☐ None	Mission Assurance Mgr.
6. Has complete as-built list information been submitted to PDMG?	☒	☐	☐		23. Open Problem Logs & P/FRs on sim. H/W and/or related S/W ☐ Attached ☒ None	System Engineer 7/13/00
7. Are required design analyses complete, up to date, approved and archived? Attach identifying list per item 29.	☒	☐	☐		24. Signed Environmental Test Authorization & Summary (ETAS) ☐ Attached ☒ None	Integration & Test Mgr. 7-13-00
8. Have all required environmental qualification tests & analyses called for in D-13144, Table 5.2 been completed?	☒	☐	☐		25. Assy/ Subsystem Power Data Sheet ☒ Attached ☐ None	Instrument Manager
9. Is all required assembly and/or subsystem level functional testing completed?	☐	☒	☐	The support equipment was not able to process the TAXI stream without errors. The problem is in the support equipment. Additional testing will be performed with new SE hardware.	26. Shortage List ☐ Attached ☒ None	Other
10. Have applicable telemetry calibration data been submitted to the System Engineer?	☐	☐	☒		27. Operational Constraints/Idiosyncrasies ☐ Attached ☒ None	Other
11. Have all required single point failure actions been taken?	☐	☐	☒		28. Requirements Verification Matrix (reference item 4) ☒ Attached ☐ None	Other
12. Have all required mass data been submitted?	☒	☐	☐		29. Design analyses completed, approved & archived (per item 7) ☐ Attached ☒ None	Other
13. Have all stress, corrosion & flammable material requirements been met ?	☒	☐	☐			Other
14. Have all piece parts, processes and materials been approved by JPL?	☒	☐	☐			Other
15. Has hardware been baked out, cleaned and met all contamination control requirements?	☐	☒	☐	Not baked out yet		Other
16. Are all required shipping containers, shipping procedures, special handling procedures, AHSE and SE ready?	☒	☐	☐			Other
17. Is this hardware acceptable for flight?	☐	☒	☐	Acceptable for integration into Integrated Electronics Module Acceptable for flight after bake out.		Other